

IN THE CLAIMS:

Please cancel claims 1–8 and 21-32 without prejudice. Please amend the remaining claims as follows, substituting any amended claim(s) for the corresponding pending claim(s):

- 1 9. (Currently Amended) An integrated circuit package, comprising:
2 an integrated circuit die mounted on a lead frame including one or more leads or pins; and
3 a plastic or epoxy material encapsulating at least part of the integrated circuit die and a
4 portion of the lead frame,
5 wherein a portion of the lead frame remaining unencapsulated by the plastic or epoxy
6 material is folded around sides of the encapsulated integrated circuit die and over or adjacent to a
7 peripheral upper surface of the plastic or epoxy material.
- 1 10. (Original) The integrated circuit package of claim 9, further comprising:
2 a connection between a ground voltage and the portion of the lead frame folded around the
3 sides of the encapsulated integrated circuit die and over or adjacent to the peripheral upper surface
4 of the plastic or epoxy material.

1 11. (Currently Amended) The integrated circuit package of claim 9, wherein the plastic or epoxy
2 material encapsulates exposed surfaces of the integrated circuit die, except for a sensing surface, and
3 wire bonds connecting the integrated circuit die to portions of the lead frame.

1 12. (Original) The integrated circuit package of claim 9, wherein portions of the lead frame are
2 folded around each side of the encapsulated integrated circuit die.

1 13. (Original) The integrated circuit package of claim 9, wherein a first portion of the lead frame
2 folded around a first side of the encapsulated integrated circuit die includes an opening providing
3 access for a connector to pins electrically connected to the integrated circuit die.

1 14. (Original) The integrated circuit package of claim 9, wherein portions of the lead frame are
2 folded only around edges of the encapsulated integrated circuit die not including leads electrically
3 connected to the integrated circuit die.

1 15. (Original) The integrated circuit package of claim 9, wherein:

2 a first portion of the lead frame is folded around a side of the encapsulated integrated circuit
3 die; and

4 a second portion of the lead frame extending from the first portion is folded over a peripheral
5 upper surface of the encapsulated integrated circuit die.

1 16. (Original) The integrated circuit package of claim 9, wherein:

2 a first portion of the lead frame is folded around a side of the encapsulated integrated circuit
3 die; and

4 a second portion of the lead frame extending from the first portion is folded adjacent to and
5 level with a peripheral upper surface of the encapsulated integrated circuit die.

1 17. (Currently Amended) An integrated circuit package, comprising:

2 a lead frame including a die paddle, one or more leads or pins, and portions extending from
3 the die paddle;

4 an integrated circuit die mounted on the die paddle;

5 a plastic or epoxy material encapsulating exposed surfaces of the integrated circuit die except
6 for a sensing surface,

7 wherein the portions of the lead frame extending from the die paddle are folded around sides
8 of the encapsulated integrated circuit die and over or adjacent to peripheral upper surfaces of the
9 encapsulated integrated circuit die.

1 18. (Currently Amended) The integrated circuit package of claim 17, wherein ~~the lead frame~~
2 ~~includes pins or leads and~~ the portions extending from the die paddle include openings around the
3 pins or leads.

1 19. (Currently Amended) The integrated circuit package of claim 17, wherein ~~the lead frame~~
2 ~~includes pins or leads and~~ the portions extending from the die paddle project from peripheral edges
3 of the die paddle not adjacent to the pins or leads.

- 1 20. (Original) A lead frame strip for an integrated circuit package, comprising:
2 at least one lead frame, the lead frame including:
3 a die paddle on which an integrated circuit will be mounted;
4 a plurality of structures which will be formed into pins or leads for the integrated
5 circuit package; and
6 portions extending from the die paddle which will be folded around sides of the
7 integrated circuit package and over or adjacent to a peripheral upper surface of the integrated
8 circuit package to form an electrostatic discharge ring.